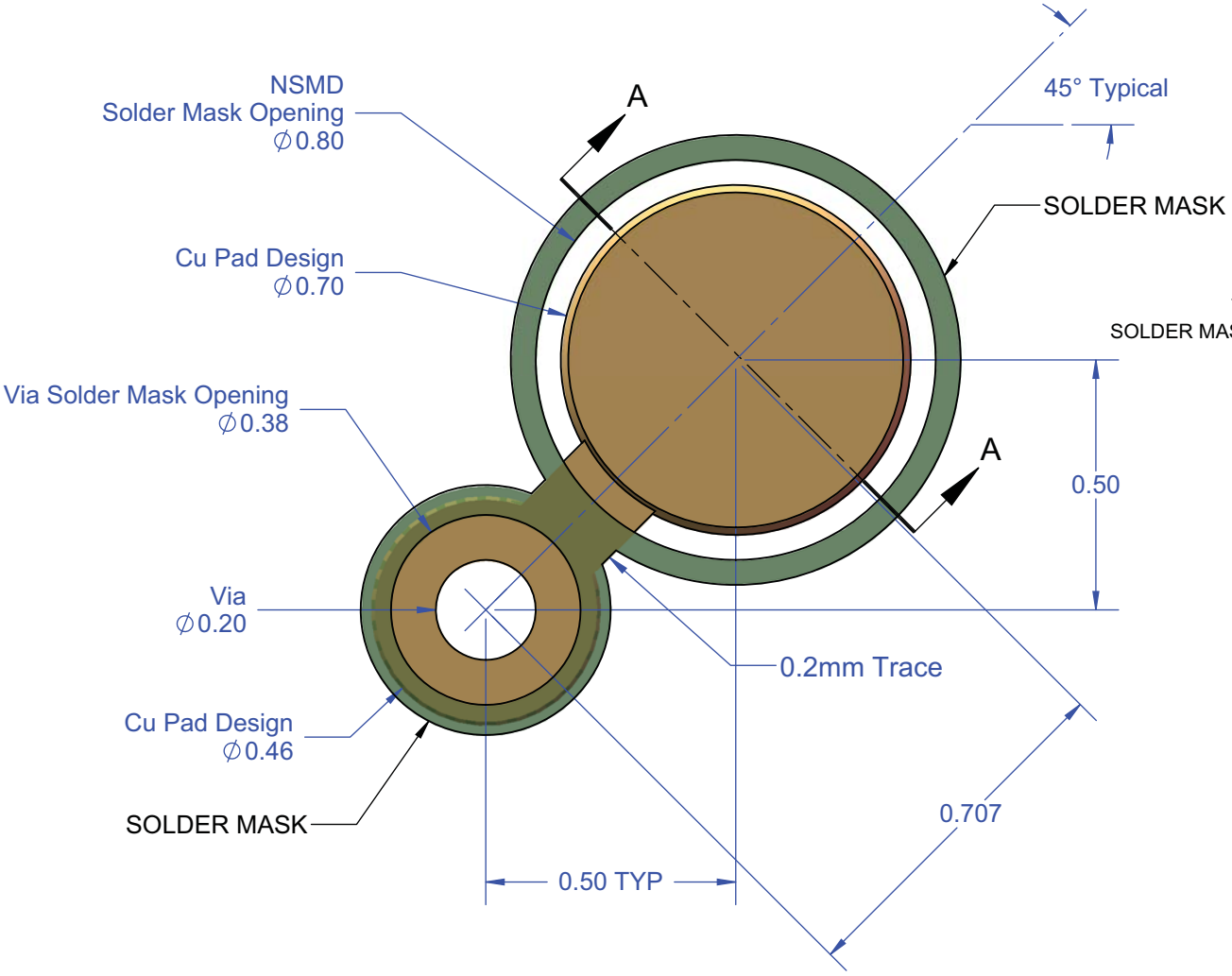
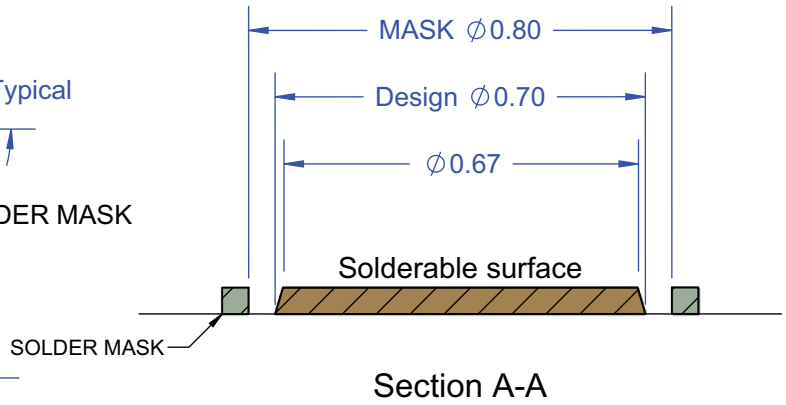
PCB PAD DESIGN RULES
CCGA PITCH 1.0MM



Cu PAD SIDE VIEW



Section A-A

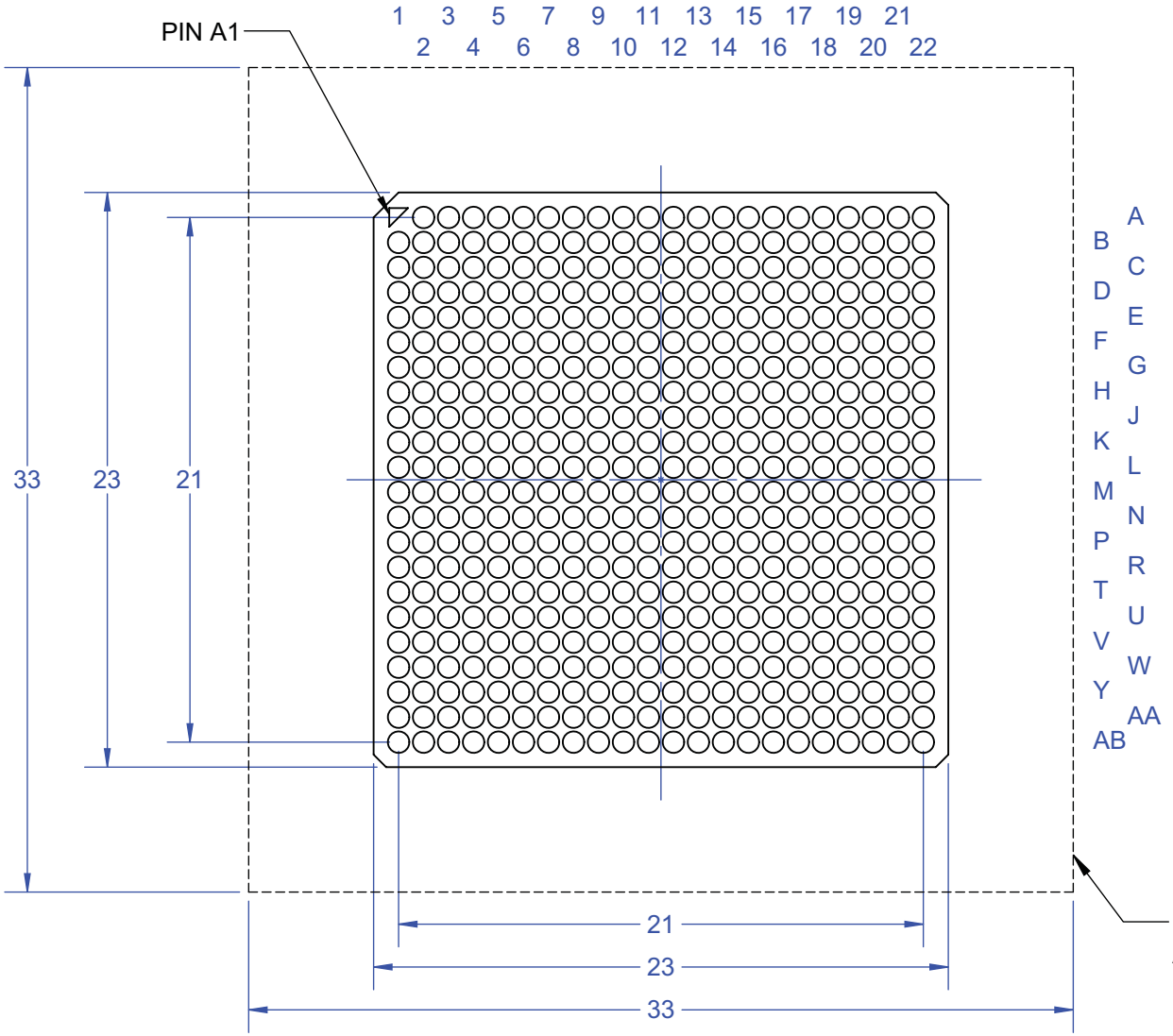
NOTES:
1. DIMENSIONS IN mm UNLESS OTHERWISE SPECIFIED.
2. SOLDERABLE SURFACE ∅0.67 IS THE FUNCTIONAL SURFACE OF Cu PAD.
3. ∅0.70 IS THE DESIGN DIMENSION OF Cu PAD.
4. PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
   DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine®

TITLE	CCGA483T1.0-DC225D PITCH 1.0mm		
SCALE 70:1	SIZE A	DRAWING NO. 160064	REV A
DO NOT SCALE DRAWING		SHEET 8 OF 9	

PCB LAND ARRAY

SHOWN WITHOUT DAISY CHAIN



SOLDER PASTE STENCIL	
Thickness	190~203µm 7.5~8.0 mil
Aperture	1:1

SOLDER PASTE VOLUME	
Nominal	0.06mm^3 4000 mils^3
Maximum	0.078mm^3 5000 mils^3
Minimum	0.031mm^3 2000 mils^3

SOLDER PASTE
Sn63/Pb37 90% solder by weight 50% solids by volume Type T3 Particle Size Flux ROL0 No Clean Paste (optional)

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TopLine®

TITLE	CCGA483T1.0-DC225D DUMMY COLUMN GRID ARRAY		
SCALE	SIZE	DRAWING NO.	REV
3.5:1	A	160064	A
DO NOT SCALE DRAWING		SHEET 9 OF 9	